IPC ASSOCIATION ELECTRONIC	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			The der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					nterials and	ials and Mfg Information			
Supplie	r Information														
Company name*				Company unique ID			Unique ID Authority				Respo	Response Date*			
nsemi											2025-0	2025-07-06			
Contact N	lame		Title - Contact			P	Phone - Contact*				Email	Email - Contact*			
Product-l	Env-Stewards		Product Enviro Compliance			ı	NA				Prod	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			P	Phone - Representative*			Email	Email - Representative*				
Product-	Env-Stewards		Product Enviro Compliance			ı	NA				Prod	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Ite		m Number Mfr Item Name				Effective Date	Date Version Manufacturing Site		;	Weight*	UOM	Unit Type		
		LM258DR2G ANA LO PWR OF		P AMP DUAL	:	2025-07-06	7-06 CNW			71.99	mg	Each			
Ianufa	acturing Proccess Inform								,				·	·	
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-02		-STD-020 MSL R	Rating	Peak Process Body Temperature Ma		Max Time at I	eak Temper	rature Numb	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed C			U Alloy 1 260 C 30 seconds 3												
omments															
vel 1 - m	naximum time at peak temper	ature during so	ldering is 10-3	30 seconds											
or more	information regarding mater	ial composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appli											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.06	mg
			Supplier	Silver (Ag)	7440-22-4		1.92	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.156	mg
			Supplier	Acrylic resins	Proprietary Data		0.264	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.2257	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.4441	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58			Epoxy resin	proprietary data		2.1435	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7145	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.1435	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		23.4356	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.18		Supplier	Palladium (Pd)	7440-05-3		0.0029	mg
			Supplier	Copper (Cu)	7440-50-8		0.1771	mg